

IN THE CLAIMS

Please amend the claims as follows:

1. (original) A method of cooling at least one electronic device, wherein a movable pumping element (4) pumps a fluid to and/or from said electronic device, and wherein the movement of said pumping element (4) is induced by heat.
2. (original) A method as claimed in claim 1, wherein said heat at least comprises heat which is produced by said electronic device.
3. (currently amended) A method as claimed in claim 1 ~~or 2~~, wherein said heat is produced by at least one heater (8).
4. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein the movement of said pumping element (4) is a pulsating and/or a vibrating movement.
5. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein fluid is compressed by the movement of said pumping element (4), wherein the compressed fluid

is cooled, and wherein the cooled fluid is transported to said at least one device.

6. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein said pumping element circulates said fluid between said at least one device (1) and fluid cooling means (5).

7. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein said fluid comprises air.

8. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein said pumping element comprises a diaphragm (4).

9. (currently amended) A method as claimed in ~~claims 5 and 8~~claim 5, wherein said fluid is supplied to a fluid compression chamber (13), wherein a first side of said diaphragm abuts said compression chamber (13), and wherein heat is supplied to a second side of said diaphragm (4) for moving the diaphragm into the compression chamber (13).

10. (currently amended) A method as claimed in ~~any one of the preceding claims~~claim 1, wherein said pumping element (4) is expanded from a first position to a second position by said heat, and wherein the expansion of said pumping element leads to pumping of said fluid.

11. (original) A method as claimed in claim 10, wherein said heat is removed from the pumping element (4) after said expansion, such that the pumping element (4) contracts to said first position.

12. (original) A system for cooling at least one electronic device, comprising at least one movable pumping element (4) for transporting a fluid to and/or from said device, wherein said pumping element (4) is movable by heat.

13. (original) A system as claimed in claim 12, wherein said pumping element comprises a diaphragm (4), for example, an expandable and contractable diaphragm (4) which is movable between at least a first position and a second position.

14. (currently amended) A system as claimed in claim 12 ~~or 13~~, comprising cooling means (5) for cooling said fluid.

15. (original) A system as claimed in claim 14, wherein said cooling means comprise expansion means for expanding compressed fluid, for example, an expansion valve (15).

16. (currently amended) A system as claimed in claim 14 ~~or 15~~, wherein said cooling means comprise a heat exchanger, particularly a cooling rib (5), for transporting heat from the fluid to the environment.

17. (currently amended) A system as claimed in ~~any one of claims 12 to 16~~claim 12, comprising a compression chamber (13) for compressing fluid, wherein a first side of said pumping element (4) abuts said compression chamber (13).

18. (original) A system as claimed in claim 17, comprising a fluid supply (2, 23) for supplying fluid from said compression chamber (13) to said electronic device (1).

19. (currently amended) A system as claimed in ~~any one of claims 12 to 18~~claim 12, comprising a heat collector (2; 102) for collecting heat from said device.

20. (original) A system as claimed in claim 19, wherein said heat collector comprises a heat pipe (102) which is connected or connectable to said pumping element (4) for supplying heat to the pumping element (4).

21. (original) A system as claimed in claim 19, wherein said heat collector comprises a fluid which is at least contained in a heat collection chamber (2).

22. (currently amended) A system as claimed in ~~any one of claims 12 to 21~~claim 12, comprising a pumping chamber (3) for pumping fluid from said device, wherein a second side of said pumping element (4) abuts said pumping chamber (3).

23. (currently amended) A system as claimed in ~~claims 21 and 22~~claim 21, wherein said pumping chamber (3) is fluid-connectable to said heat collection chamber (2).

24. (currently amended) A system as claimed in ~~at least claims 17 and 22~~claim 17, wherein said pumping chamber (3) is fluid-connectable to said compression chamber (13), for example, by means of a fluid connection (22) which comprises a one-way valve (11, 17).

25. (currently amended) A system as claimed in ~~any one of claims 12 to 24~~claim 12, comprising at least one heater (8) for providing at least a part of the heat for moving said pumping element (4).

26. (currently amended) A system as claimed in ~~claims 22 and 25~~claim 22, wherein said heater (8) is at least arranged to heat the content of said pumping chamber (3).

27. (currently amended) A system as claimed in ~~any one of claims 12 to 26~~claim 12, comprising valve means (15, 17, 7, 11) which are arranged to control the transport of said fluid.

28. (original) A system as claimed in claim 27, wherein at least a part of said valve means is arranged to cooperate with said pumping element (4) for controlling the transport of said fluid, and wherein, for example, said cooperation is mechanical, electric, electronic or the like.

29. (currently amended) A system as claimed in ~~any one of claims 12 to 28~~claim 12, wherein at least a part of the system is arranged to be mounted on or near an electronic device for cooling said device.

30. (currently amended) A system as claimed in ~~any one of claims 12 to 29~~claim 12, wherein the pumping element (4) is arranged to carry out a pumping movement under the influence of a heat-induced pressure rise.

31. (currently amended) A system as claimed in ~~any one of claims 12 to 30~~claim 12, wherein the pumping element is arranged to carry out a pumping movement when the temperature of the pumping element changes.

32. (currently amended) An electronic device provided with and/or coupled to a system as claimed in ~~any one of claims 12 to 31~~claim 12, wherein the electronic device is particularly part of a computing means, a computer, a server and/or the like.

33. (currently amended) An apparatus provided with a system as claimed in ~~any one of claims 12 to 31~~claim 12.